

## 60 V 100 mA Low Power Voltage Regulator for Industrial Applications

No. EY-397-190606

### OVERVIEW

The R1561x is a CMOS-based low power voltage regulator featuring 60 V input voltage and 100 mA output current. The device includes a short current limit circuit, an overcurrent protection circuit and a thermal shutdown. These features make the R1561x an ideal constant voltage power source for industrial applications. This is a high-reliability semiconductor device for industrial applications (-Y) that has passed both the screening at high temperature and the reliability test with extended hours. This line of products operate in a wide temperature range from low temperature to high temperature to support harsh environment applications.

### KEY BENEFITS

- Low power consumption and excellent transient response help to provide stable power supply.
- The input voltage range is as wide as 5.5 V to 60 V, and the output voltage accuracy is as high as  $\pm 0.8\%$ .
- High heat dissipation and space-saving HSOP-6J and TO-252-5-P2 packages.

### KEY SPECIFICATIONS

- Input Voltage Range (Max. Rating): 5.5 V to 60 V (80 V)
- Operating Temperature Range:  $-50^{\circ}\text{C}$  to  $125^{\circ}\text{C}$
- Supply Current: Typ. 20  $\mu\text{A}$
- Dropout Voltage: Typ. 1.3 V  
( $I_{\text{OUT}} = 100 \text{ mA}$ ,  $V_{\text{OUT}} = 5.0 \text{ V}$ )
- Output Voltage Accuracy:  $\pm 0.8\%$  ( $T_a = 25^{\circ}\text{C}$ )
- Temp. Coefficient of Output Voltage: Typ.  $\pm 100 \text{ ppm}/^{\circ}\text{C}$
- Line Regulation: Typ.  $0.01\%/V$  ( $6 \text{ V} \leq V_{\text{IN}} \leq 60 \text{ V}$ )
- Short-circuit Current Limiting: limits to Typ. 50 mA
- Overcurrent Protection: triggers at Typ. 150 mA
- Thermal Shutdown: triggers at Typ.  $165^{\circ}\text{C}$

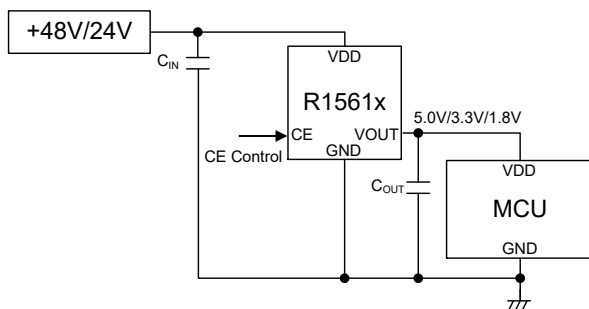
### SELECTION GUIDE

Product Name	Package
R1561Sxx1B-E2-YE	HSOP-6J
R1561Jxx1B-T1-YE	TO-252-5-P2

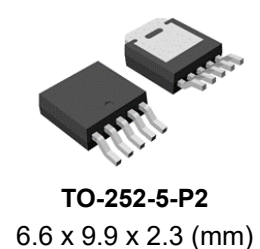
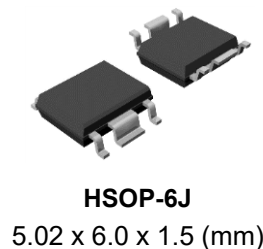
xx: Set Output Voltage ( $V_{\text{SET}}$ )

1.8 V (18) / 2.5 V (25) / 2.8 V (28) / 3.0 V (30) / 3.3 V (33) / 3.4 V (34) / 5.0 V (50) / 7.0 V (70) / 8.0 V (80) / 9.0 V (90) / 10.0 V (A0) / 12.0 V (C0) / 14.0 V (E0)

### TYPICAL APPLICATIONS



### PACKAGES



### APPLICATIONS

- FA Equipment, Smart meters
- Surveillance Cameras and Vending Machines that are used under high-temperature conditions

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## R1561x-Y

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### SELECTION GUIDE

The output voltage and the package type are user-selectable options.

#### Selection Guide

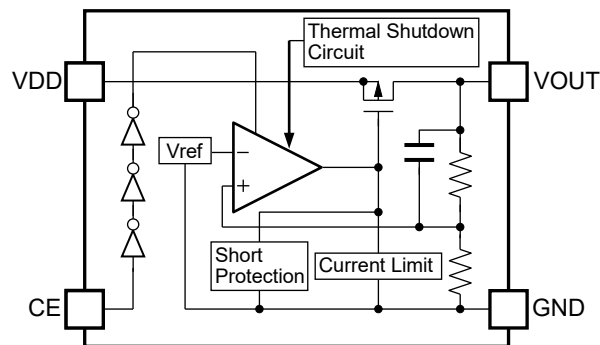
Product Name	Package	Quantity per Reel	Pb Free	Halogen Free
R1561Sxx1B-E2-YE	HSOP-6J	1,000 pcs	Yes	Yes
R1561Jxx1B-T1-YE	TO-252-5-P2	3,000 pcs	Yes	Yes

xx: Set Output Voltage ( $V_{SET}$ )

1.8 V (18) / 2.5 V (25) / 2.8 V (28) / 3.0 V (30) / 3.3 V (33) / 3.4 V (34) / 5.0 V (50) /  
7.0 V (70) / 8.0 V (80) / 9.0 V (90) / 10.0 V (A0) / 12.0 V (C0) / 14.0 V (E0)

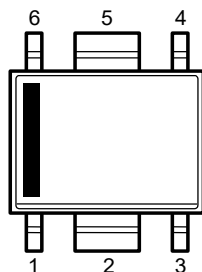
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### BLOCK DIAGRAM

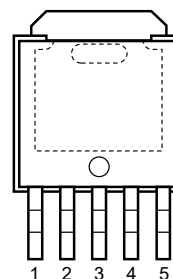


R1561x Block Diagram

## PIN DESCRIPTIONS



HSOP-6J Pin Configuration



TO-252-5-P2 Pin Configuration

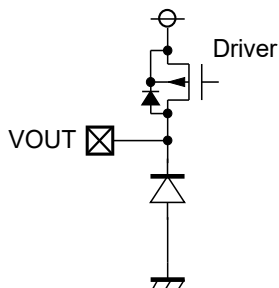
### HSOP-6J Pin Description

Pin No.	Pin Name	Description
1	VOUT	Output Pin
2	GND <sup>(1)</sup>	Ground Pin
3	CE	Chip Enable Pin, Active-high
4	GND <sup>(1)</sup>	Ground Pin
5	GND <sup>(1)</sup>	Ground Pin
6	VDD	Input Pin

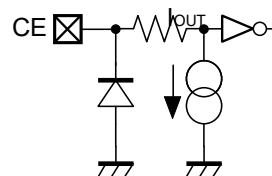
### TO-252-5-P2 Pin Description

Pin No.	Pin Name	Description
1	VDD	Input Pin
2	NC	No Connection
3	GND	Ground Pin
4	VOUT	Output Pin
5	CE	Chip Enable Pin, Active-high

### Pin Equivalent Circuit Diagrams



VOUT Pin Equivalent Circuit Diagram



CE Pin Equivalent Circuit Diagram

<sup>(1)</sup> The GND pins are connected to each other on the board.

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## ABSOLUTE MAXIMUM RATINGS

### Absolute Maximum Ratings

Symbol	Parameter		Rating	Unit	
V <sub>IN</sub>	Input Voltage		-0.3 to 80	V	
V <sub>IN</sub>	Peak Inrush Voltage <sup>(1)</sup>		90	V	
V <sub>CE</sub>	CE Pin Input Voltage		-0.3 to 80	V	
V <sub>OUT</sub>	Output Voltage		-0.3 to V <sub>IN</sub> + 0.3 ≤ 80	V	
I <sub>OUT</sub>	Output Current		150	mA	
P <sub>D</sub>	Power Dissipation <sup>(2)</sup>	HSOP-6J	JEDEC STD.51-7	3400	mW
		TO-252-5-P2	JEDEC STD.51-7	4800	
T <sub>j</sub>	Junction Temperature		-50 to 150	°C	
T <sub>stg</sub>	Storage Temperature Range		-55 to 150	°C	

### ABSOLUTE MAXIMUM RATINGS

Electronic and mechanical stress momentarily exceeded absolute maximum ratings may cause permanent damage and may degrade the life time and safety for both device and system using the device in the field. The functional operation at or over these absolute maximum ratings is not assured.

## RECOMMENDED OPERATING CONDITIONS

### Recommended Operating Conditions

Symbol	Parameter	Rating	Unit
V <sub>IN</sub>	Input Voltage	5.5 to 60	V
T <sub>a</sub>	Operating Temperature Range	-50 to 125	°C

### RECOMMENDED OPERATING CONDITONS

All of electronic equipment should be designed that the mounted semiconductor devices operate within the recommended operating conditions. The semiconductor devices cannot operate normally over the recommended operating conditions, even if they are used over such conditions by momentary electronic noise or surge. And the semiconductor devices may receive serious damage when they continue to operate over the recommended operating conditions.

<sup>(1)</sup> Duration: 200 ms or less

<sup>(2)</sup> Refer to *POWER DISSIPATION* for detailed information.

## ELECTRICAL CHARACTERISTICS

$C_{IN} = 0.1 \mu\text{F}$  /  $C_{OUT} = 10 \mu\text{F}$ , unless otherwise noted.

The specifications surrounded by   are guaranteed by design engineering at  $-50^\circ\text{C} \leq T_a \leq 125^\circ\text{C}$ .

### R1561x Electrical Characteristics

( $T_a = 25^\circ\text{C}$ )

Symbol	Parameter	Test Conditions/Comments		Min.	Typ.	Max.	Unit
I <sub>SS</sub>	Supply Current	V <sub>IN</sub> = 14 V V <sub>CE</sub> = 14 V I <sub>OUT</sub> = 0 mA	V <sub>SET</sub> ≤ 5.0 V		20.0	<span style="border: 1px solid black; padding: 0 2px;">30.0</span>	μA
		V <sub>IN</sub> = 18 V V <sub>CE</sub> = 18 V I <sub>OUT</sub> = 0 mA	V <sub>SET</sub> > 5.0 V		23.0	<span style="border: 1px solid black; padding: 0 2px;">38.0</span>	
I <sub>standby</sub>	Standby Current	V <sub>IN</sub> = 60 V, V <sub>CE</sub> = 0 V			0.1	<span style="border: 1px solid black; padding: 0 2px;">2.0</span>	μA
V <sub>OUT</sub>	Output Voltage	V <sub>SET</sub> ≤ 5.0 V V <sub>IN</sub> = 14 V I <sub>OUT</sub> = 1 mA	T <sub>a</sub> = 25°C	×0.992		×1.008	V
			-50°C ≤ T <sub>a</sub> ≤ 125°C	<span style="border: 1px solid black; padding: 0 2px;">×0.985</span>		<span style="border: 1px solid black; padding: 0 2px;">×1.015</span>	
		V <sub>SET</sub> > 5.0 V V <sub>IN</sub> = 18 V I <sub>OUT</sub> = 1 mA	T <sub>a</sub> = 25°C	×0.988		×1.012	
			-50°C ≤ T <sub>a</sub> ≤ 125°C	<span style="border: 1px solid black; padding: 0 2px;">×0.980</span>		<span style="border: 1px solid black; padding: 0 2px;">×1.020</span>	
ΔV <sub>OUT</sub> / ΔI <sub>OUT</sub>	Load Regulation	V <sub>IN</sub> = 8 V (V <sub>SET</sub> ≤ 5.0 V) V <sub>IN</sub> = V <sub>SET</sub> + 3 V (V <sub>SET</sub> > 5.0 V) 1 mA ≤ I <sub>OUT</sub> ≤ 100 mA		Refer to Voltage-specific Electrical Characteristics			
ΔV <sub>OUT</sub> / ΔV <sub>IN</sub>	Line Regulation	6 V ≤ V <sub>IN</sub> ≤ 60 V I <sub>OUT</sub> = 1 mA	V <sub>SET</sub> ≤ 5.0 V	<span style="border: 1px solid black; padding: 0 2px;">-0.02</span>	0.01	<span style="border: 1px solid black; padding: 0 2px;">0.02</span>	%V
		V <sub>SET</sub> +1 V ≤ V <sub>IN</sub> ≤ 60 V I <sub>OUT</sub> = 1 mA	V <sub>SET</sub> > 5.0 V	<span style="border: 1px solid black; padding: 0 2px;">-0.02</span>	0.01	<span style="border: 1px solid black; padding: 0 2px;">0.02</span>	
V <sub>DIF</sub>	Dropout Voltage	I <sub>OUT</sub> = 100 mA		Refer to Voltage-specific Electrical Characteristics			
I <sub>LIM</sub>	Output Current Limit	V <sub>IN</sub> = 8.0 V (V <sub>SET</sub> ≤ 5.0 V) V <sub>IN</sub> = V <sub>SET</sub> + 3 V (V <sub>SET</sub> > 5.0 V)		<span style="border: 1px solid black; padding: 0 2px;">100</span>	150	<span style="border: 1px solid black; padding: 0 2px;">250</span>	mA
I <sub>SC</sub>	Short-circuit Current	V <sub>IN</sub> = 8.0 V (V <sub>SET</sub> ≤ 5.0 V) V <sub>IN</sub> = V <sub>SET</sub> + 3 V (V <sub>SET</sub> > 5.0 V) V <sub>OUT</sub> = 0 V		<span style="border: 1px solid black; padding: 0 2px;">20</span>	50	<span style="border: 1px solid black; padding: 0 2px;">75</span>	mA
V <sub>CEH</sub>	CE Input Voltage "H"	V <sub>IN</sub> = 60 V		<span style="border: 1px solid black; padding: 0 2px;">3.0</span>		60	V
V <sub>CEL</sub>	CE Input Voltage "L"	V <sub>IN</sub> = 60 V		0		<span style="border: 1px solid black; padding: 0 2px;">0.3</span>	V
I <sub>PD</sub>	CE Pull-down Current	V <sub>IN</sub> = 60 V, V <sub>CE</sub> = 3 V			0.4	<span style="border: 1px solid black; padding: 0 2px;">0.8</span>	μA
T <sub>TSD</sub>	Thermal Shutdown Temperature	Junction Temperature		<span style="border: 1px solid black; padding: 0 2px;">150</span>	165		°C
T <sub>TSR</sub>	Thermal Shutdown Release Temperature <sup>(1)</sup>	Junction Temperature		<span style="border: 1px solid black; padding: 0 2px;">125</span>	135		°C

All parameters are tested under the pulse load condition (T<sub>j</sub> ≈ T<sub>a</sub> = 25°C).

<sup>(1)</sup> If the VDD and CE pins are turned on at the same time when T<sub>a</sub> > 125°C, the thermal shutdown can be activated.

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**R1561x-Y**

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**R1561x Product-specific Electrical Characteristics**

(Ta = 25°C)

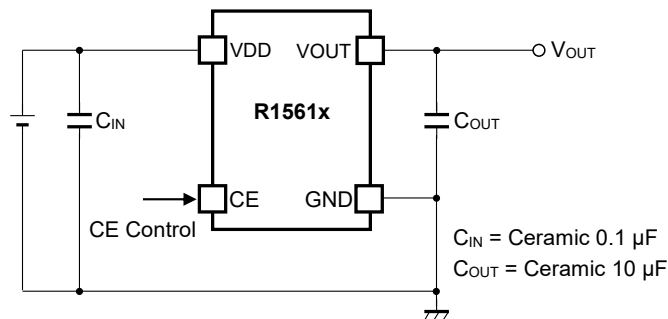
Product Name	V <sub>OUT</sub> (V) (Ta = 25°C)			V <sub>OUT</sub> (V) (-50°C ≤ Ta ≤ 125°C)			ΔV <sub>OUT</sub> /ΔI <sub>OUT</sub> (mV)			V <sub>DIF</sub> (V)	
	Min.	Typ.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.	Typ.	Max.
R1561x181B	1.7856	1.80	1.8144	<u>1.7730</u>	1.80	<u>1.8270</u>	-30	3	30	3.7	<u>4.0</u>
R1561x251B	2.4800	2.50	2.5200	<u>2.4625</u>	2.50	<u>2.5375</u>				3.0	<u>3.6</u>
R1561x281B	2.7776	2.80	2.8224	<u>2.7580</u>	2.80	<u>2.8420</u>				2.7	<u>3.6</u>
R1561x301B	2.9760	3.00	3.0240	<u>2.9550</u>	3.00	<u>3.0450</u>				2.5	<u>3.6</u>
R1561x331B	3.2736	3.30	3.3264	<u>3.2505</u>	3.30	<u>3.3495</u>				2.2	<u>3.0</u>
R1561x341B	3.3728	3.40	3.4272	<u>3.3490</u>	3.40	<u>3.4510</u>				2.1	<u>3.0</u>
R1561x501B	4.9600	5.00	5.0400	<u>4.9250</u>	5.00	<u>5.0750</u>				1.3	<u>2.5</u>
R1561x701B	6.9160	7.00	7.0840	<u>6.8600</u>	7.00	<u>7.1400</u>	-40	4	40	1.3	<u>2.5</u>
R1561x801B	7.9040	8.00	8.0960	<u>7.8400</u>	8.00	<u>8.1600</u>				1.3	<u>2.5</u>
R1561x901B	8.8920	9.00	9.1080	<u>8.8200</u>	9.00	<u>9.1800</u>				1.3	<u>2.5</u>
R1561xA01B	9.8800	10.00	10.120	<u>9.8000</u>	10.0	<u>10.200</u>				1.3	<u>2.5</u>
R1561xC01B	11.856	12.00	12.144	<u>11.760</u>	12.0	<u>12.240</u>				1.3	<u>2.5</u>
R1561xE01B	13.832	14.00	14.168	<u>13.720</u>	14.0	<u>14.280</u>				1.3	<u>2.5</u>

## THEORY OF OPERATION

### Thermal Shutdown

If the junction temperature increases above 165°C (Typ.), the operation of the regulator would stop. And if the junction temperature decreases below 135°C (Typ.), the operation of the regulator would restart. Unless the causes of temperature rising are removed, the regulator repeats turning on and off and the output waveform becomes a pulse shape.

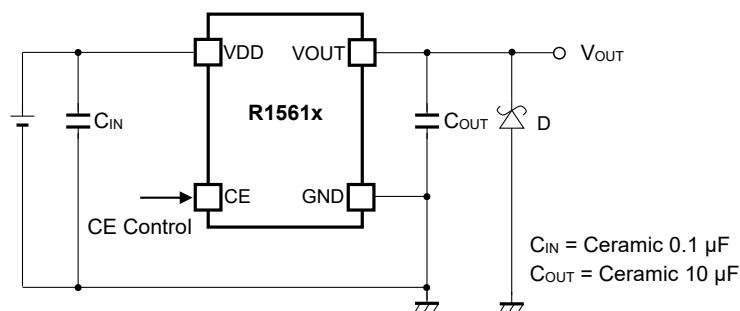
## APPLICATION INFORMATION



**R1561x Typical Applications**

### Typical Application for IC Chip Breakdown Prevention

When a sudden surge of electrical current travels along the VOUT pin and GND due to a short-circuit, electrical resonance of a circuit involving an output capacitor ( $C_{OUT}$ ) and a short circuit inductor generates a negative voltage and may damage the device or the load devices. Connecting a schottky diode (D) between the VOUT pin and GND has the effect of preventing damage to them.



**R1561x Typical Application for IC Chip Breakdown Prevention**

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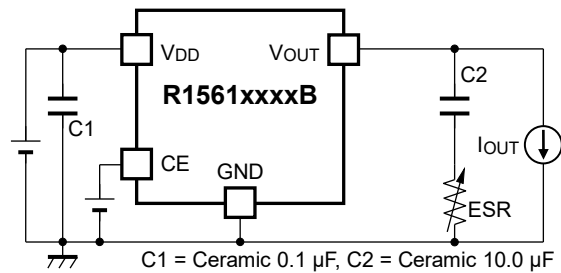
## R1561x-Y

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### Equivalent Series Resistance vs. Output Current

It is recommended that a ceramic type capacitor be used for this device. However, other types of capacitors having lower ESR can also be used. The relation between the output current ( $I_{OUT}$ ) and the ESR of output capacitor is shown below.



### Measurement Conditions

Frequency Band: 10 Hz to 2 MHz

Measurement Temperature:  $-40^{\circ}\text{C}$  to  $125^{\circ}\text{C}$

Capacitor: C1 = Ceramic 0.1  $\mu$ F, C2 = Ceramic 10.0  $\mu$ F

ESR: 0 to 100  $\Omega$

$V_{OUT}$ : 1.8 V, 5.0 V

It is confirmed that the output noise level is less than the specified value (40  $\mu$ Vrms) under the measurement conditions above.



## TECHNICAL NOTES

The performance of a power source circuit using this device is highly dependent on a peripheral circuit. A peripheral component or the device mounted on PCB should not exceed its rated voltage, rated current or rated power. When designing a peripheral circuit, please be fully aware of the following points.

### Phase Compensation

A phase compensation is provided to secure stable operation even when the load current is varied. For this purpose, use a 10- $\mu$ F or more output capacitor ( $C_{OUT}$ ) with good frequency characteristics and proper ESR (Equivalent Series Resistance). In case of using a tantalum type capacitor with a large ESR, the output might become unstable. Evaluate your circuit including consideration of frequency characteristics. Connect a 0.1- $\mu$ F or more input capacitor ( $C_{IN}$ ) between the VDD and GND pins with shortest-distance wiring.

### PCB Layout

As for the HSOP-6J package, ensure that the GND pins (Pin No. 2, 4 and 5) are connected to each other and the ground plane.

### Operating the Device below the Minimum Operating Voltage

Operating the device below the recommended operating voltage range can make the output voltage unstable and make the output voltage higher than the set output voltage ( $V_{SET}$ ) of the device.

In the case of turning on the VIN and CE pins at the same time, both pins must be turned on using a 100-V/ms or more slew rate in order to prevent the unstable operation upon start-up. In the case of turning on the VIN pin using a 100-V/ms or less slew rate, the CE pin must be turned on after the supply voltage becomes 5.5 V or more.

In the case of turning off the VIN and CE pins at the same time, both pins must be turned off using a steep slew rate, -100 V/ms or higher in order to prevent the unstable operation. In the case of turning off the VIN pin using a slow rate, lower than -100 V/ms, the CE pin must be turned off before the supply voltage decreases to 5.5 V.

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## R1561x-Y

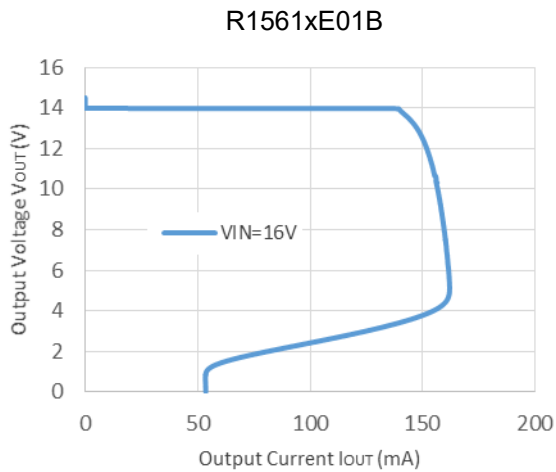
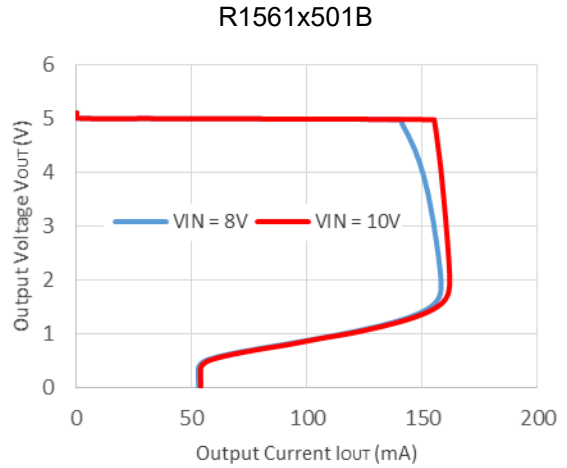
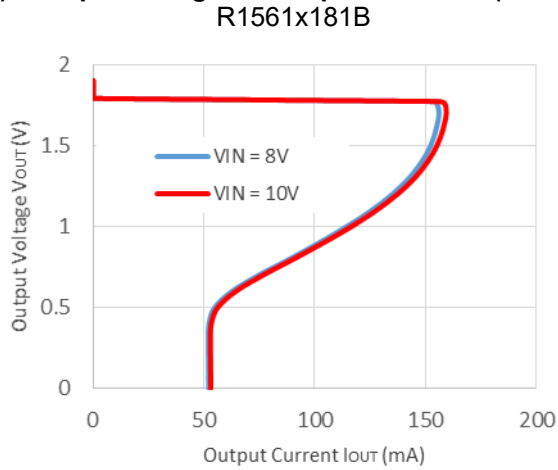
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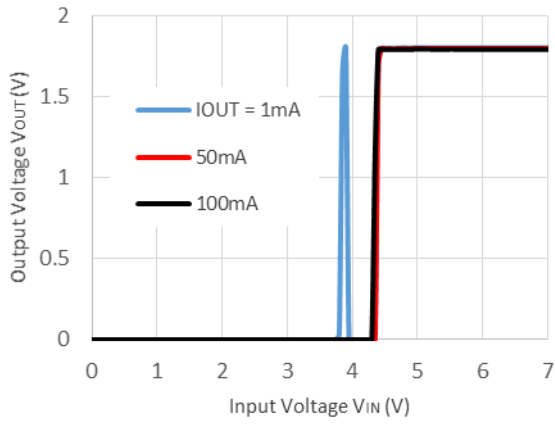
### TYPICAL CHARACTERISTICS

Note: Typical Characteristics are intended to be used as reference data; they are not guaranteed.

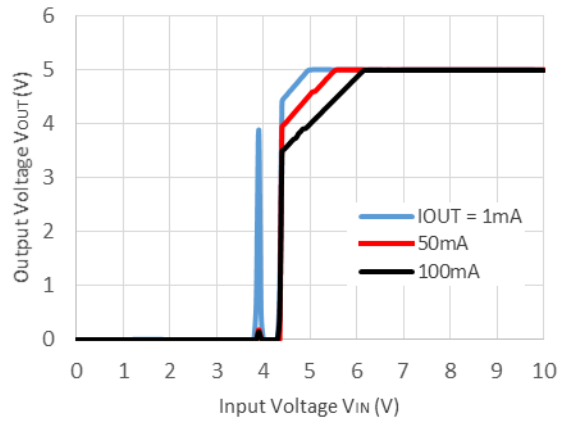
#### 1) Output Voltage vs. Output Current (Ta = 25°C)



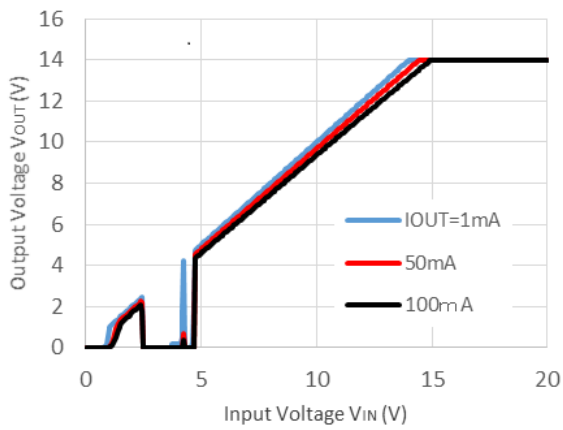
2) Output Voltage vs. Input Voltage (Ta = 25°C)  
R1561x181B



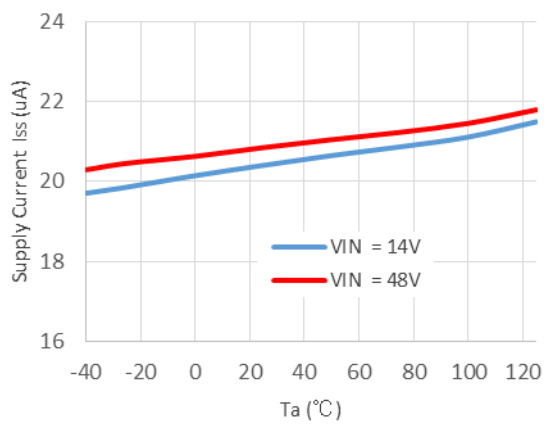
R1561x501B



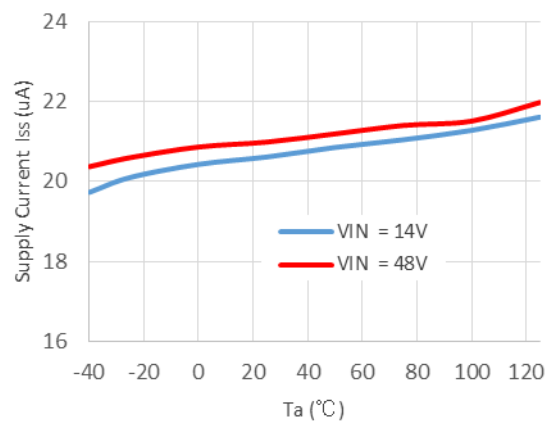
R1561xE01B



3) Supply Current vs. Temperature  
R1561x181B



R1561x501B

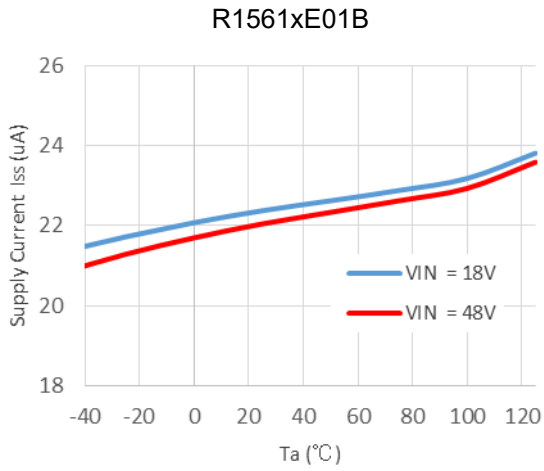


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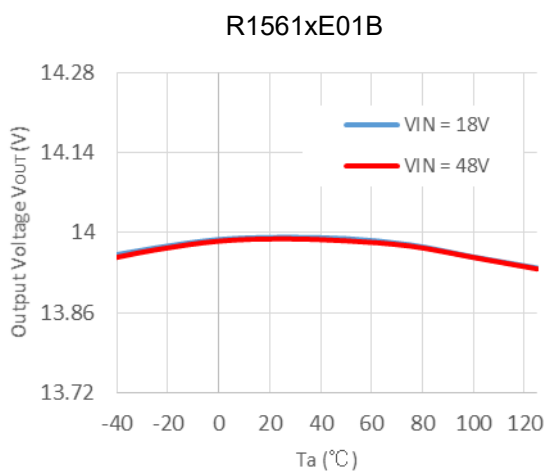
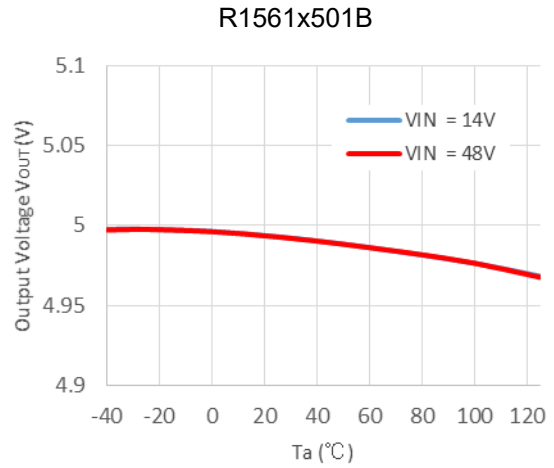
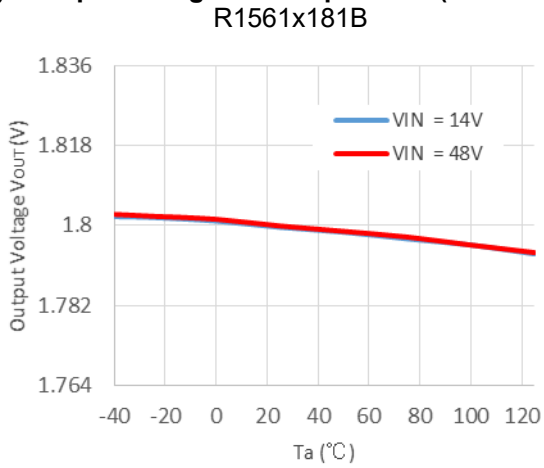
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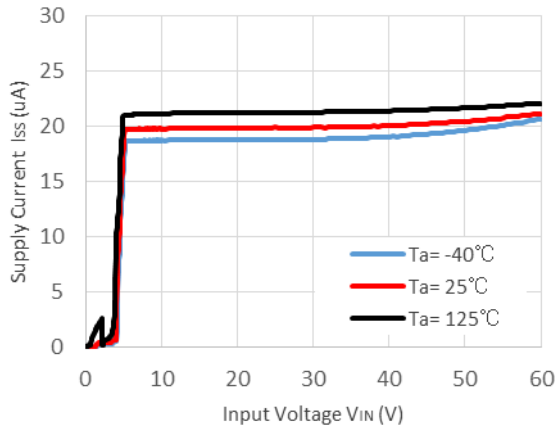
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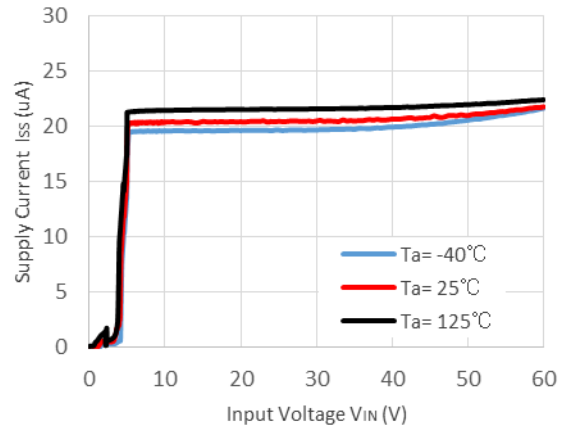
#### 4) Output Voltage vs. Temperature ( $I_{OUT} = 1 \text{ mA}$ )



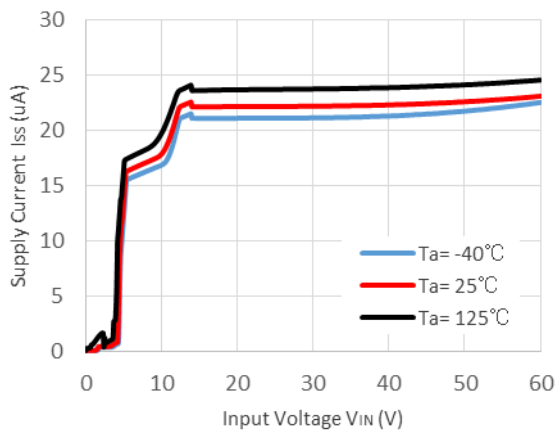
5) Supply Current vs. Input Voltage  
R1561x181B



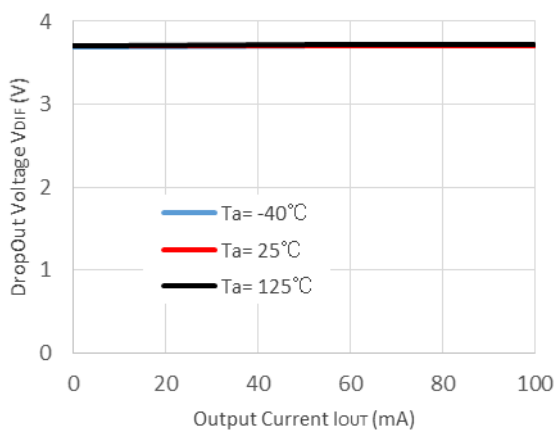
R1561x501B



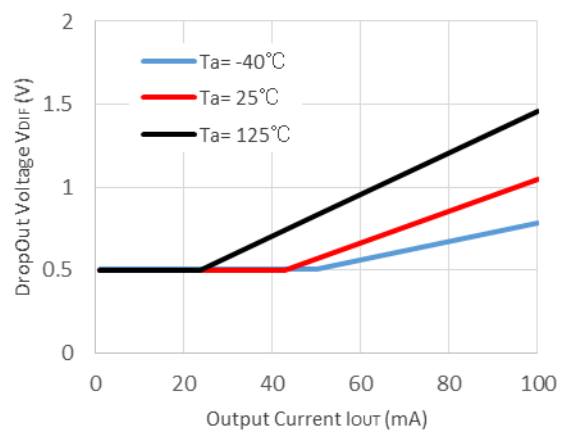
R1561xE01B



6) Dropout Voltage vs. Output Current  
R1561x181B



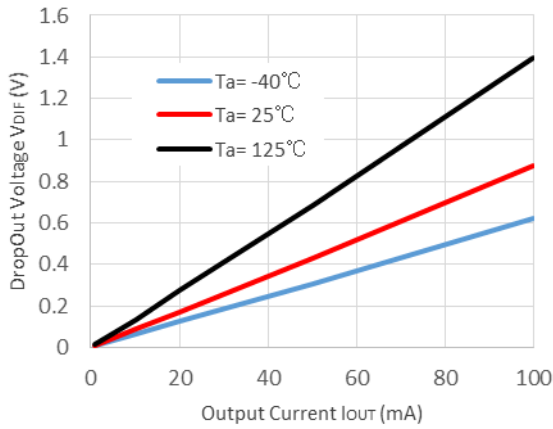
R1561x501B



# R1561x-Y

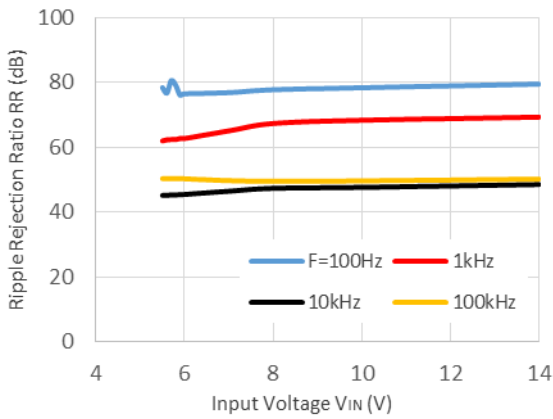
No. EY-397-190606

R1561xE01B

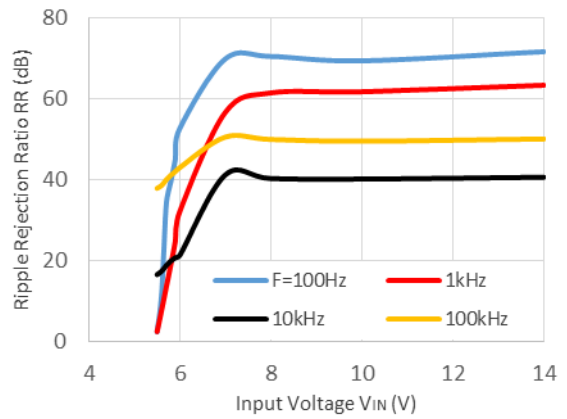


## 7) Ripple Rejection vs. Input Bias Voltage ( $T_a = 25^\circ\text{C}$ , $V_{RIPPLE} = \pm 0.2\text{ V}$ , $C_{OUT} = 10\ \mu\text{F}$ )

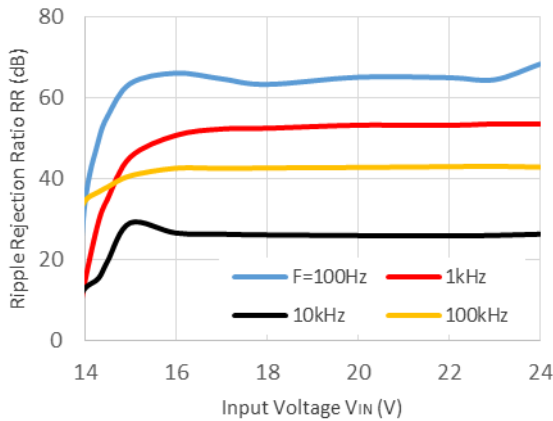
R1561x181B



R1561x501B



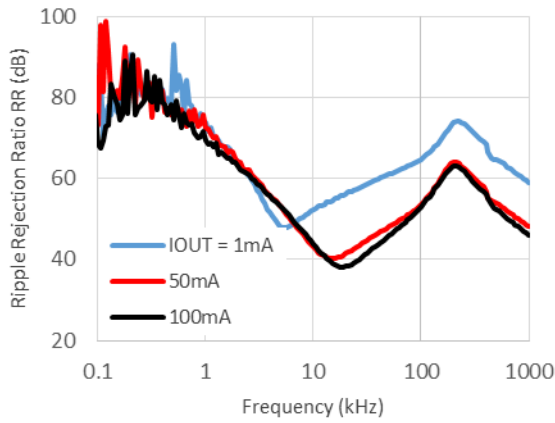
R1561xE01B



**8) Ripple Rejection vs. Frequency (Ta = 25°C, COUT = 10 µF)**

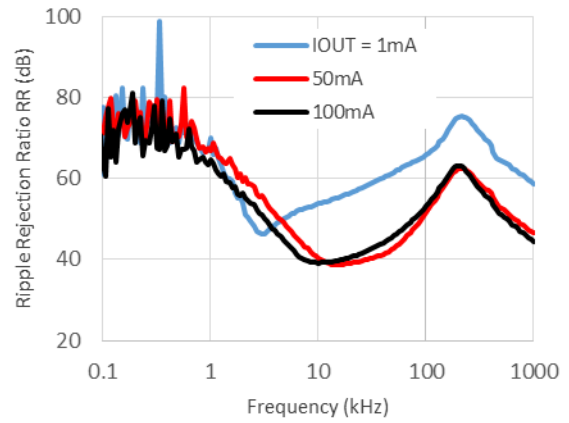
R1561x181B

VIN = 14 V ± 0.2 V ripple



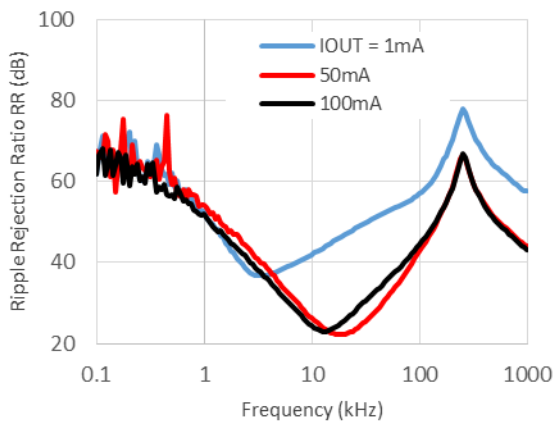
R1561x501B

VIN = 14 V ± 0.2 V ripple



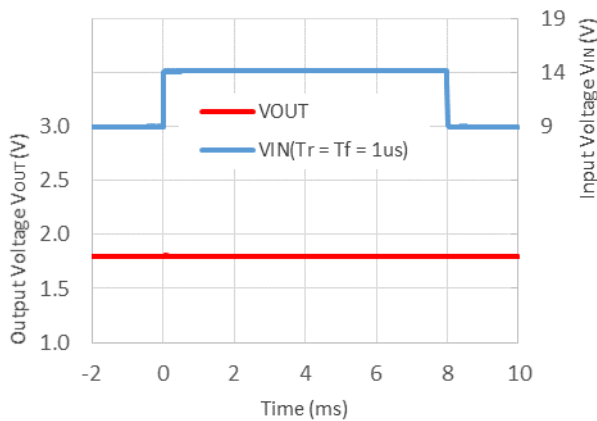
R1561xE01B

VIN = 18 V ± 0.2 V ripple

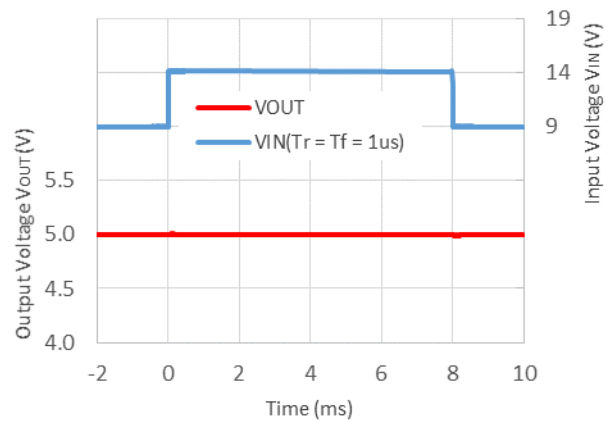


**9) Input Transient Response (Ta = 25°C, IOUT = 1 mA, COUT = 10 µF)**

R1561x181B



R1561x501B

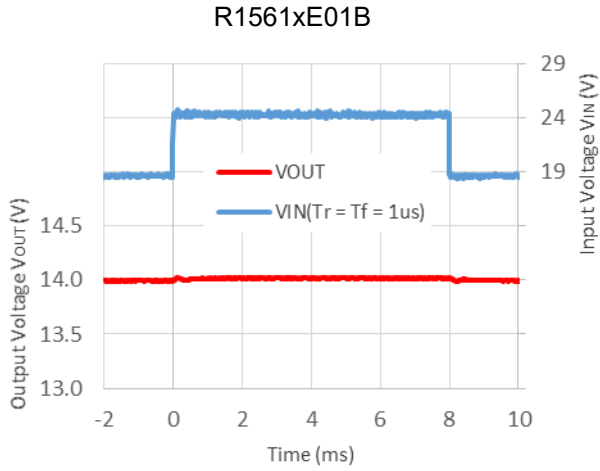


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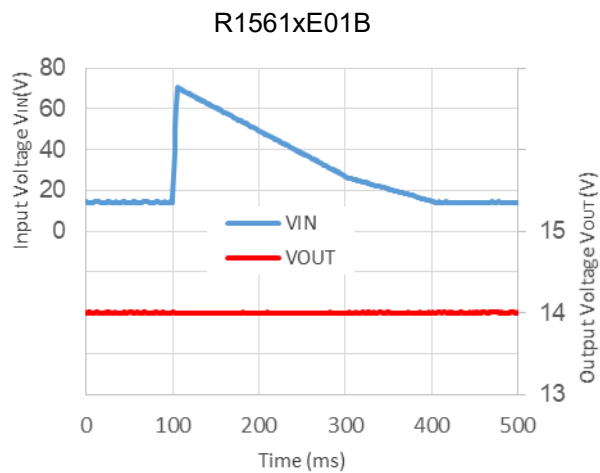
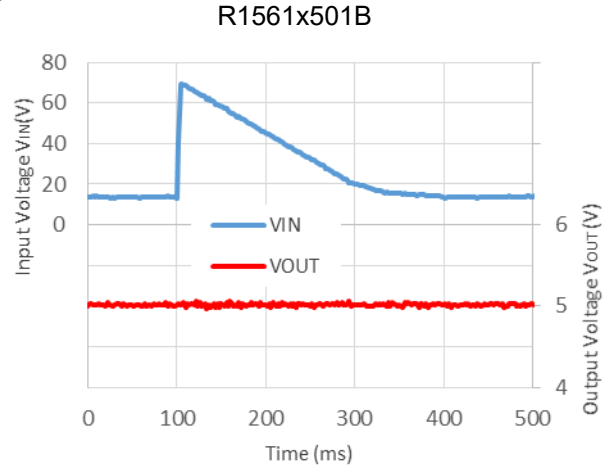
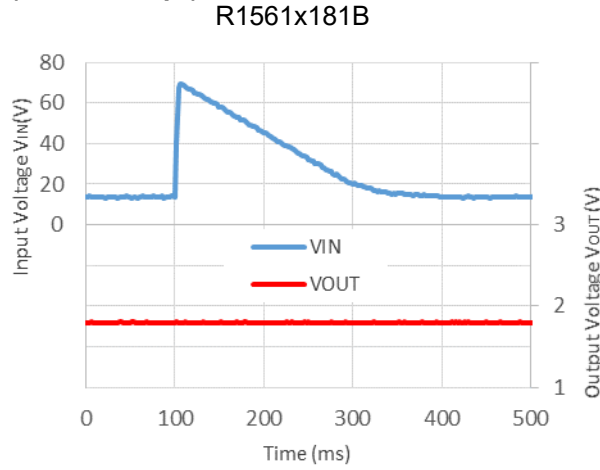
## R1561x-Y

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### 10) Load Dump ( $T_a = 25^\circ\text{C}$ , $I_{OUT} = 1\text{ mA}$ , $C_{OUT} = 10\ \mu\text{F}$ )

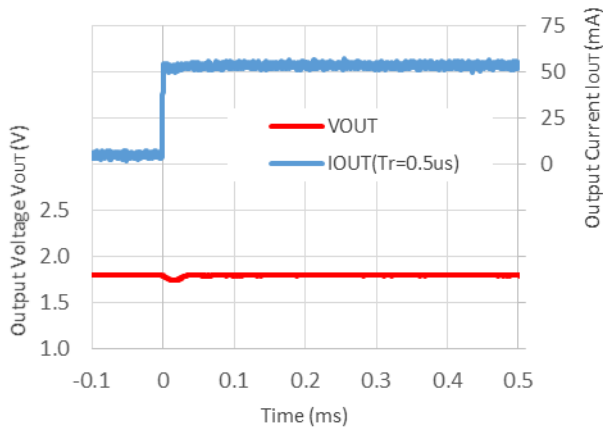




**11) Load Transient Response ( $T_a = 25^\circ\text{C}$ ,  $I_{OUT} = 1\text{ mA} \leftrightarrow 50\text{ mA}$ ,  $C_{OUT} = 10\text{ }\mu\text{F}$ )**

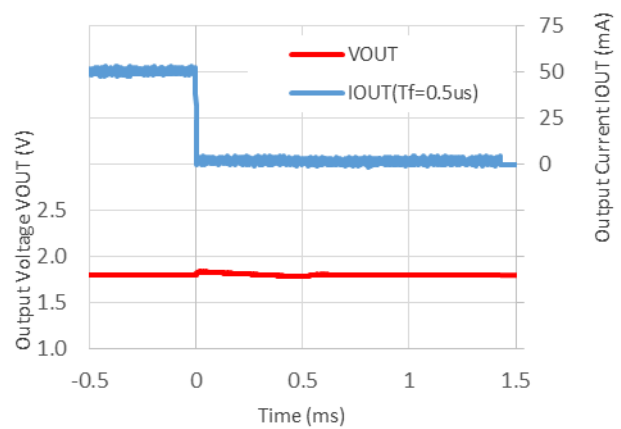
R1561x181B

$V_{IN} = 14\text{ V}$ ,  $I_{OUT} = 1\text{ mA} \rightarrow 50\text{ mA}$



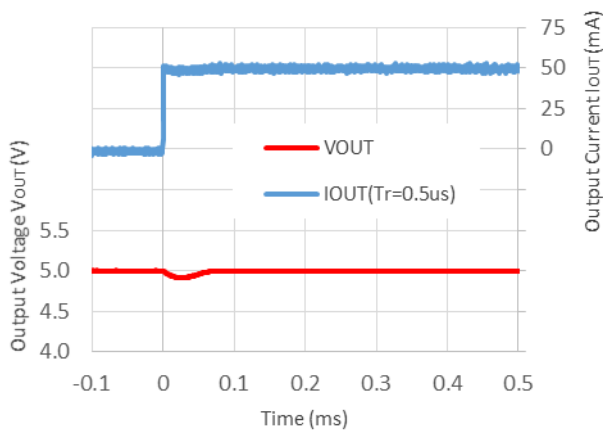
R1561x181B

$V_{IN} = 14\text{ V}$ ,  $I_{OUT} = 50\text{ mA} \rightarrow 1\text{ mA}$



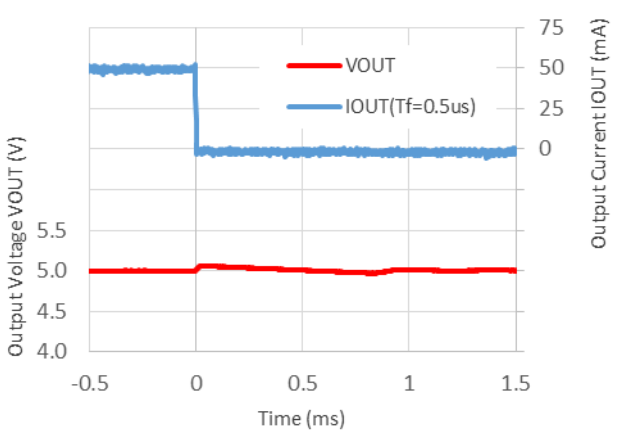
R1561x501B

$V_{IN} = 14\text{ V}$ ,  $I_{OUT} = 1\text{ mA} \rightarrow 50\text{ mA}$



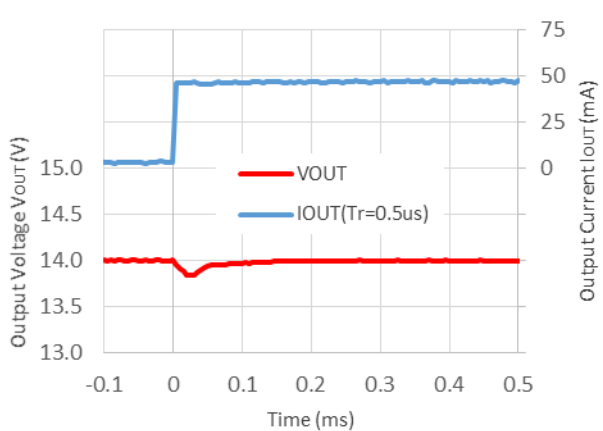
R1561x501B

$V_{IN} = 14\text{ V}$ ,  $I_{OUT} = 50\text{ mA} \rightarrow 1\text{ mA}$



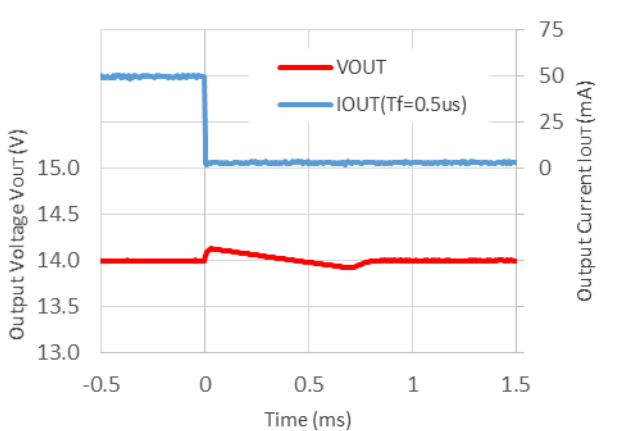
R1561xE01B

$V_{IN} = 18\text{ V}$ ,  $I_{OUT} = 1\text{ mA} \rightarrow 50\text{ mA}$



R1561xE01B

$V_{IN} = 18\text{ V}$ ,  $I_{OUT} = 50\text{ mA} \rightarrow 1\text{ mA}$



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## R1561x-Y

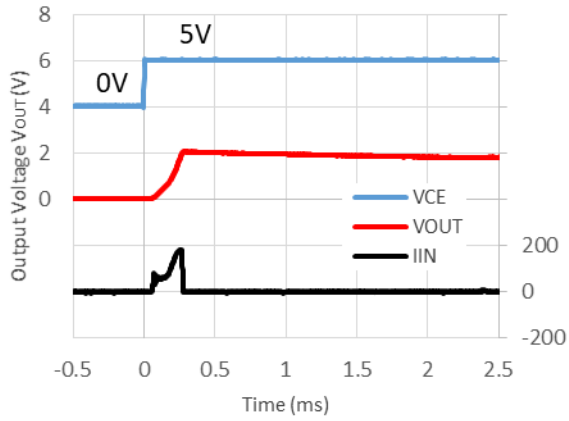
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### 12) CE Start-up ( $T_a = 25^\circ\text{C}$ )

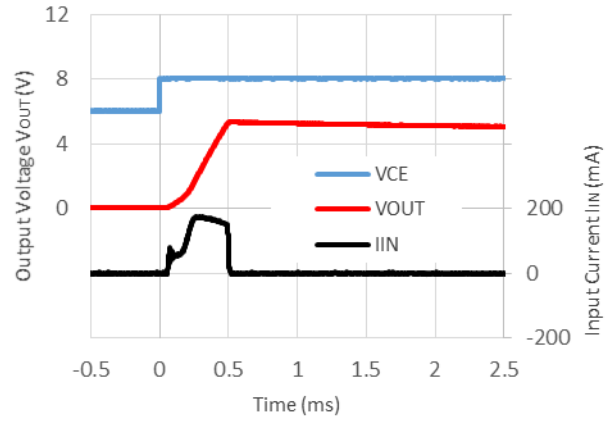
R1561x181B

$V_{IN} = 14\text{ V}$ ,  $C_{OUT} = 10\ \mu\text{F}$



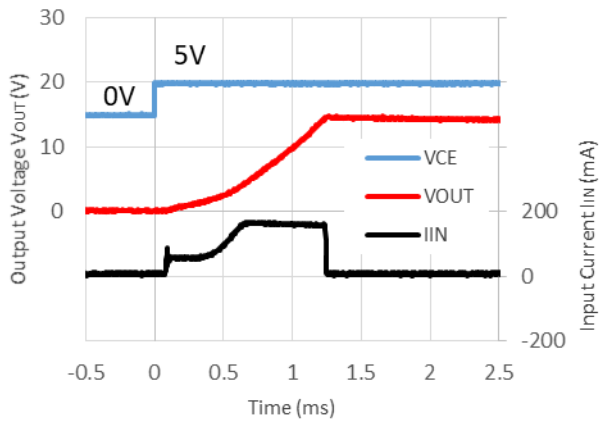
R1561x501B

$V_{IN} = 14\text{ V}$ ,  $C_{OUT} = 10\ \mu\text{F}$



R1561xE01B

$V_{IN} = 18\text{ V}$ ,  $C_{OUT} = 10\ \mu\text{F}$



The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51-7.

**Measurement Conditions**

Item	Measurement Conditions
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm
Copper Ratio	Outer Layer (First Layer): Less than 95% of 50 mm Square Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square Outer Layer (Fourth Layer): Approx. 100% of 50 mm Square
Through-holes	φ 0.3 mm × 28 pcs

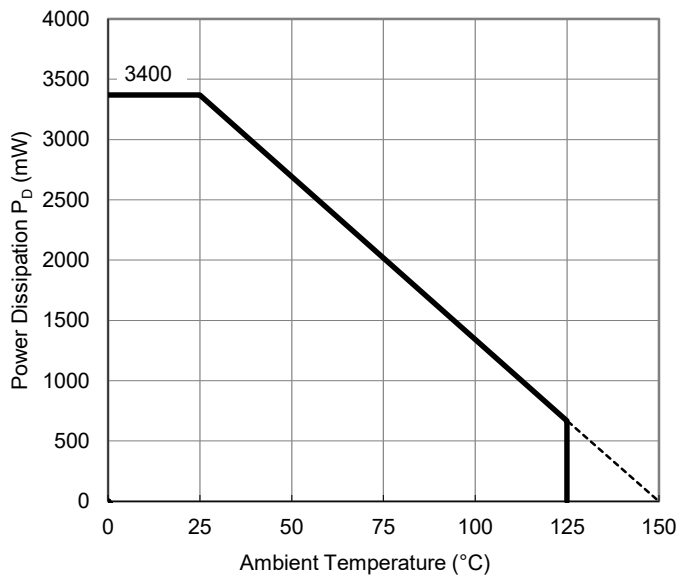
**Measurement Result**

(Ta = 25°C, Tjmax = 150°C)

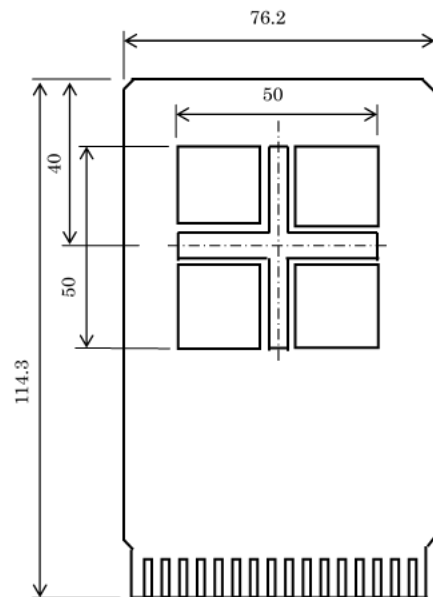
Item	Measurement Result
Power Dissipation	3400 mW
Thermal Resistance ( $\theta_{ja}$ )	$\theta_{ja} = 37^{\circ}\text{C/W}$
Thermal Characterization Parameter ( $\psi_{jt}$ )	$\psi_{jt} = 7^{\circ}\text{C/W}$

$\theta_{ja}$ : Junction-to-Ambient Thermal Resistance

$\psi_{jt}$ : Junction-to-Top Thermal Characterization Parameter



**Power Dissipation vs. Ambient Temperature**



**Measurement Board Pattern**



The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51-7.

**Measurement Conditions**

Item	Measurement Conditions
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm
Copper Ratio	Outer Layer (First Layer): Less than 95% of 50 mm Square Inner Layers (2nd, 3rd, 4th Layers: Approx. 100% of 50 mm Square
Through-holes	φ 0.3 mm × 21 pcs

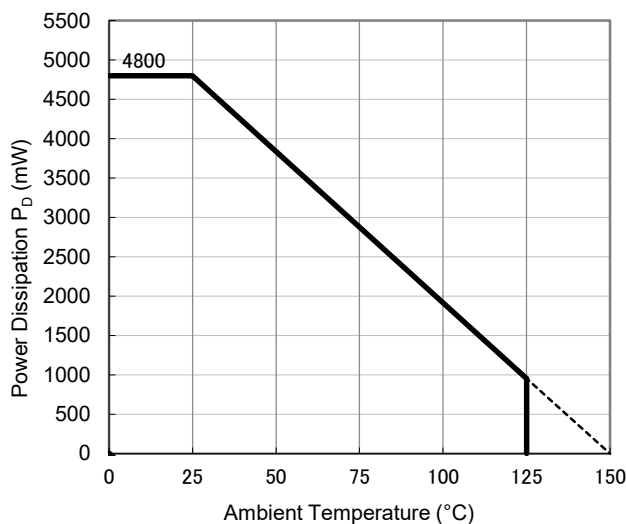
**Measurement Result**

(Ta = 25°C, Tjmax = 150°C)

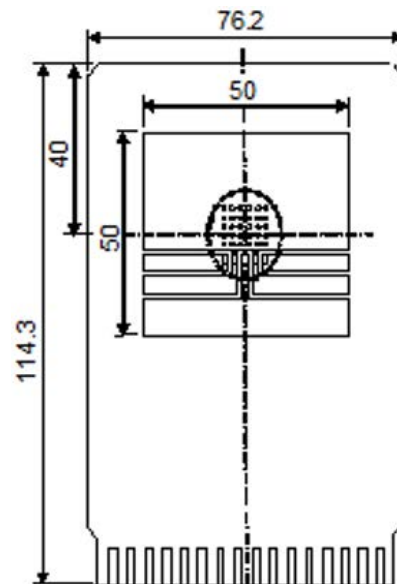
Item	Measurement Result
Power Dissipation	4800 mW
Thermal Resistance (θja)	θja = 26°C/W
Thermal Characterization Parameter (ψjt)	ψjt = 7°C/W

θja: Junction-to-Ambient Thermal Resistance

ψjt: Junction-to-Top Thermal Characterization Parameter



**Power Dissipation vs. Ambient Temperature**



**Measurement Board Pattern**





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